

Dual RX DPHY GEN2 Aggregation: 2 x RX2L → 1 x RX4L

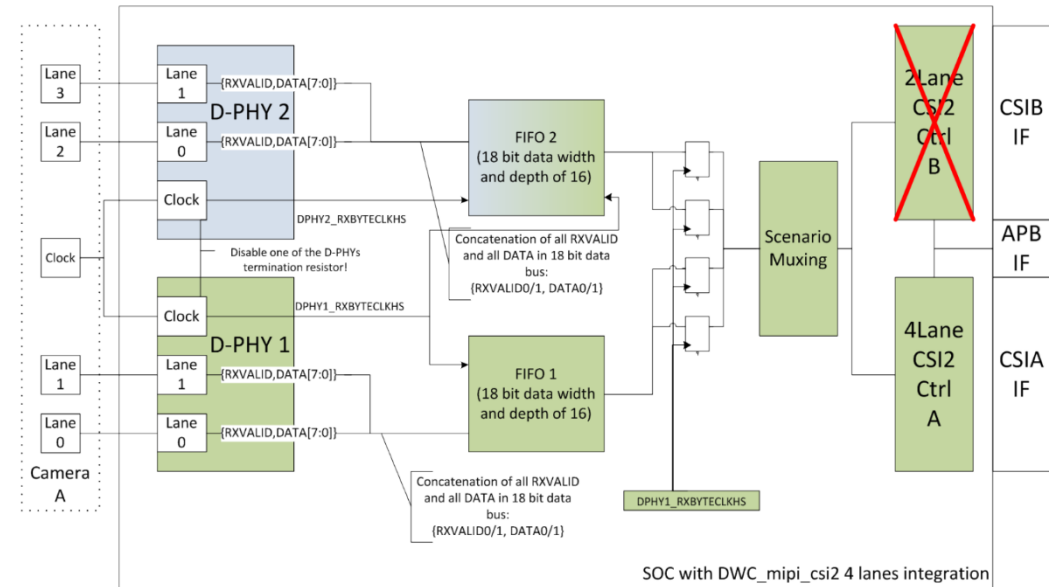
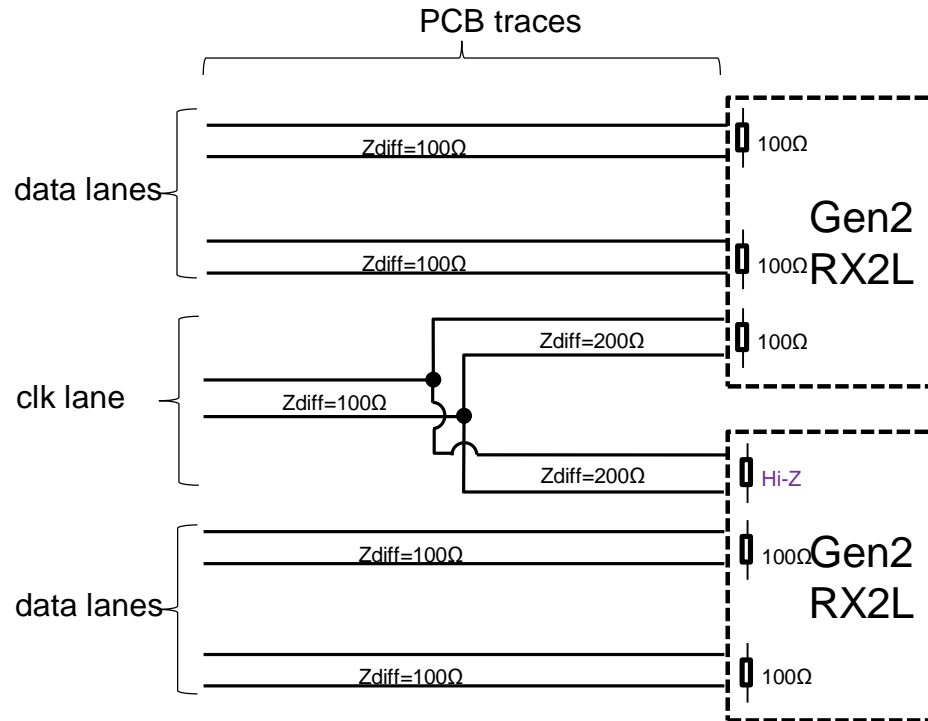
PCB Implementation



Gen2 DPHY Implementation

for 2 x RX2L → 1 x RX4L application scenario

- Two independent RX clock lanes used, single TX clock lane source
 - Silicon validated in-house and by customer on previous DPHY Generation (Gen2)
 - Input DDR clock is provided to two clock lanes



Previous DPHY generation – silicon validated

Package Implementation

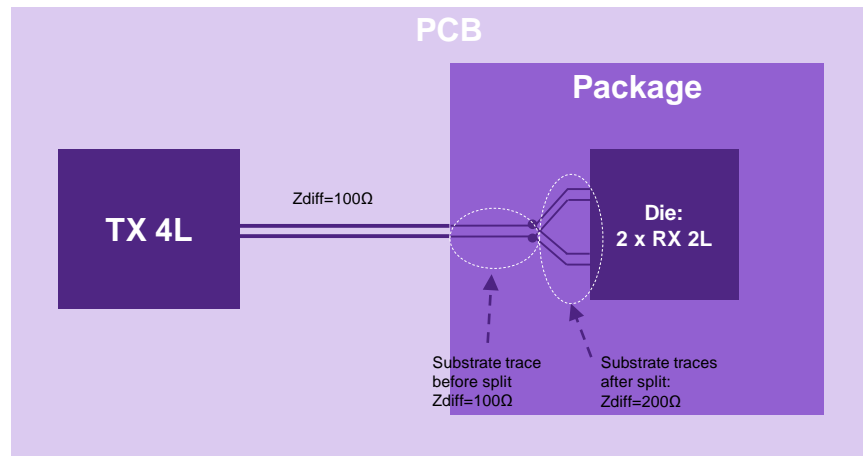
Workaround

- Adds PCB complexity and cost
 - Sets an inferior limit on cost efficiency of PCB: 200Ohm differential impedance translates to
 - Thin line width
 - Additional layer for thicker dielectric between signal plane and ground plane
 - Large line space
 - Needs careful analysis on SI issues
 - Clock Jitter → PHY performance
 - EMI
 - Noise
 - Cross-talk
- Consideration of cost efficiency may impede dual RX aggregation in practice

Package Implementation

Workaround

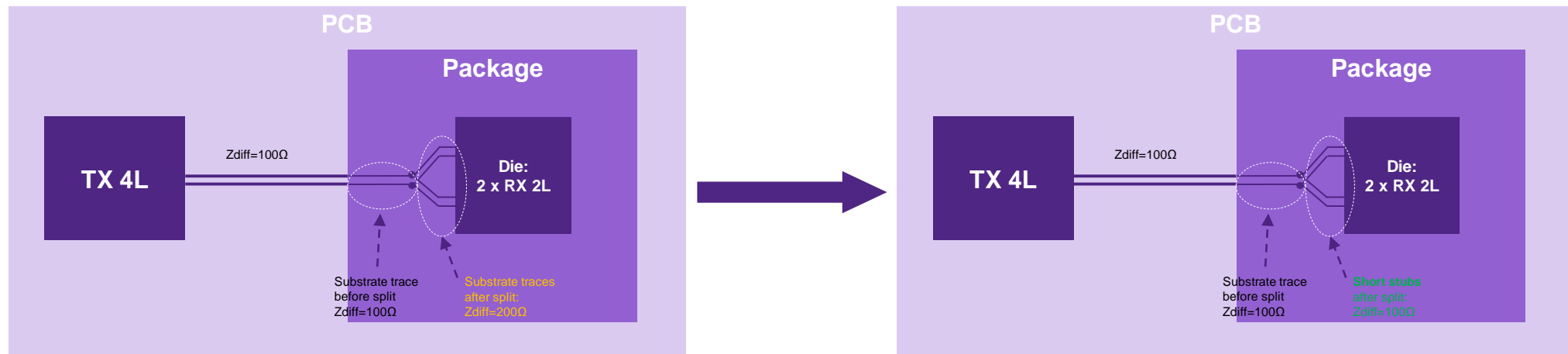
- Split clock lane on package substrate instead
 - Concept:
 - 100Ω differential impedance clock lane on PCB
 - Clock lane split to two 200Ω differential impedance traces for matched impedance
 - Pros: reduced PCB complexity and cost
 - Cons: increased package complexity and cost



Package Implementation

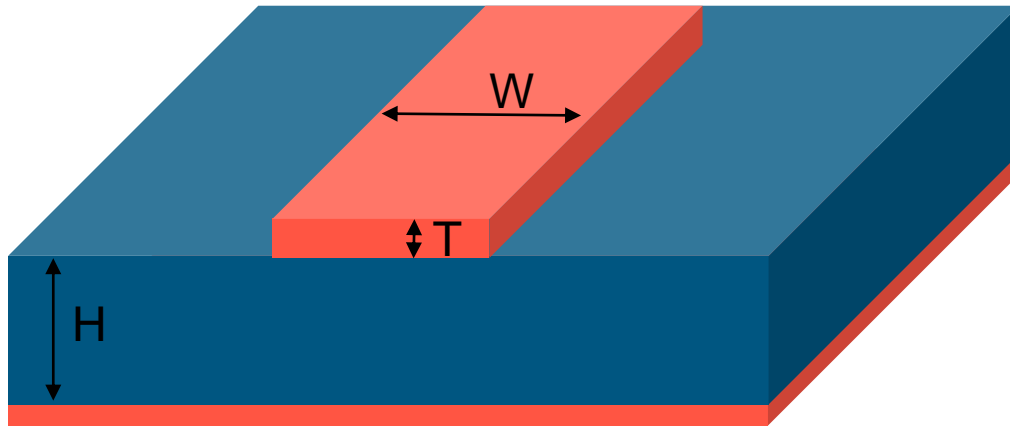
Workaround

- To reduce complexity/cost furthermore
 - 200Ω differential impedance can be optional, if a stub < 5mm after clock split point
 - No showstopper impact is expected based on first-order analysis
 - SI simulation is still mandatory to give pass/fail result for assessment of IP performance



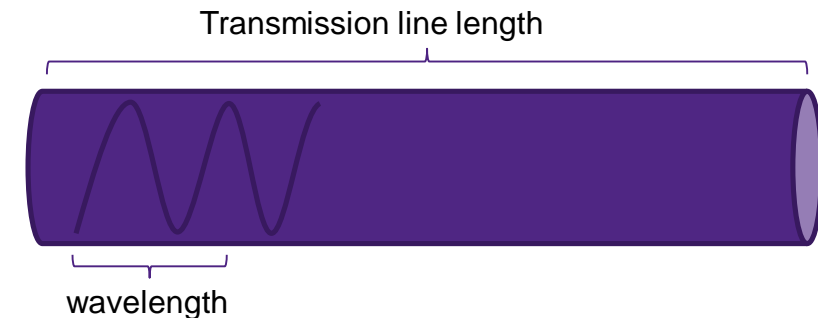
First-order Analysis

Impact of short stub



- Example: FR4 dielectric constant = 4.5
- $\text{tpd} = \frac{\sqrt{4.5}}{3 \times 10^8} = 7.07 \text{ ns/m}$
- In a typical microstrip configuration the dielectric constant is a “mix” between $\epsilon_{\text{air}} = 1$ and $\epsilon_r = 4.5$

- In a typical transmission line the phase of the signal is not constant across the path:
 - signal wavelength \ll line length
 - There is a finite velocity for the propagation of the signal, usually specified as the propagation delay:
 - $\text{tpd} = \frac{\sqrt{\epsilon_r}}{c}$, c = velocity of light
 - There is a characteristic impedance of the line that is “seen” by the signal. This impedance is real (purely resistive) and depends on the geometry of the lines.



First-order Analysis

Impact of short stub

- Transmission lines can be simplified into a discrete element if the length is “electrically small”, i.e. the signal phase is constant across the element
 - Criteria 1 – **Rule of thumb** – stub should be smaller than $\frac{1}{4}$ wavelength of f_{\max} (f_{\max} up to 5th harmonic for high speed serial links):
 - Example: $f_{\text{clk}} = 0.75\text{GHz} \rightarrow f_{\max} = 3.75\text{GHz} \rightarrow \text{period} = 0.266\text{ns}$
 - $t_{\text{pd}} = 5.6 \text{ ns/m}$
 - $\frac{1}{4} \text{ wavelength} = 0.266 / (4 * 5.6) = 11.8 \text{ mm}$
 - Criteria 2 – **Conservative estimate** – stub should be smaller than $\frac{1}{16}$ of signal “risetime”
 - Example: $f_{\text{clk}} = 0.75\text{GHz} \rightarrow \text{risetime} = 333\text{ps}$
 - $t_{\text{pd}} = 5.6 \text{ ns/m}$
 - risetime “length” = $0.333 / 5.6 = 59.6\text{mm}$
 - $1/16$ of risetime “length” = 3.7mm

Thank You



